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Edition 1.0 2019-06

INTERNATIONAL STANDARD

NORME INTERNATIONALE

Semiconductor devices –
Part 16-6: Microwave integrated circuits – Frequency multipliers

Dispositifs à semiconducteurs –
Partie 16-6: Circuits intégrés hyperfréquences – Multiplicateurs de fréquence

IEC 60747-16-6:2019-06(en-fr)

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FOREWORD

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International Standard IEC 60747-16-6 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this International Standard is based on the following documents:

CDV	Report on voting
47E/602/CDV	47E/622A/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

The French version of this standard has not been voted upon.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60747 series, published under the general title *Semiconductor devices,* can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

SEMICONDUCTOR DEVICES –

Part 16-6: Microwave integrated circuits – Frequency multipliers

1 Scope

This part of IEC 60747 specifies the terminology, essential ratings and characteristics, and measuring methods of microwave integrated circuit frequency multipliers.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60617, *Graphical symbols for diagrams* (available at http://std.iec.ch/iec60617>)

IEC 60747-1:2006, *Semiconductor devices – Part 1: General*
IEC 60747-1:2006/AMD 1:2010

IEC 60747-4, *Semiconductor devices – Discrete devices – Part 4: Microwave diodes and transistors*

IEC 60747-16-3:2002, *Semiconductor devices – Part 16-3: Microwave integrated circuits – Frequency converters*
IEC 60747-16-3:2002/AMD 1:2009
IEC 60747-16-3:2002/AMD 2:2017

IEC 61340-5-1, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC TR 61340-5-2, *Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

3.1
output frequency
f_o
frequency which equals the input frequency multiplied by the multiplying factor N, where N is an integer

3.2
output power
P_o
RF power measured at the output port at the output frequency

3.3
conversion gain
G_c
ratio of the output power to the input power

3.4
input return loss
$L_{ret(in)}$
ratio of the incident power at the input port to the reflected power at the input port

3.5
output return loss
$L_{ret(out)}$
ratio of the incident power at the output port to the reflected power at the output port

3.6
fundamental isolation
P_o/P_1
ratio of the output power to the power of fundamental component at the input frequency at the output port

3.7
n-th order harmonic isolation
P_o/P_{nth}
ratio of the output power to the power of the n-th order harmonic component at the output port

3.8
phase noise
$\mathscr{L}(f)$
frequency-domain measure of the short-term frequency stability of an output

Note 1 to entry: This phase noise is normally expressed as the power spectral density of the phase fluctuations, $S_\phi(f)$, where the phase fluctuation function is $\phi(t) = 2\pi Ft - 2\pi F_0 t$. The spectral density of phase fluctuation can be directly related to the spectral density of frequency fluctuation by the following formula:

$$S_\phi(f) = \left(\frac{F_0}{f}\right) S_y(f) \qquad \text{rad}^2/\text{Hz}$$

where

F is the output frequency;

F_0 is the average output frequency;

f is the Fourier frequency.

Note 2 to entry: $\mathscr{L}(f)$ is pronounced "script-ell of f".

[SOURCE: IEC 60050-561:2014, 561-03-22, modified – A symbol and Note 2 to entry have been added. "Oscillator" has been replaced by "output."]

4 Essential ratings and characteristics

4.1 General requirements

4.1.1 Circuit identification and types

The identification of type (device name), the category of circuit and technology applied shall be given.

Microwave frequency multipliers comprise one category.

4.1.2 General function description

A general description of the function performed by the integrated circuit microwave frequency multipliers and the features for the application shall be made.

4.1.3 Manufacturing technology

The manufacturing technology, for example semiconductor monolithic integrated circuit, thin film integrated circuit, micro-assembly. shall be stated. This statement shall include details of the semiconductor technologies such as Schottky-barrier diode, metal-semi-conductor-field-effect-transistor (MESFET), Si bipolar transistor.

IEC 60747-4 shall be referred to for terminology and letter symbols, essential ratings and characteristics and measuring methods of such microwave devices.

4.1.4 Package identification

The following statements shall be made:

a) chip or packaged form;
b) IEC and/or national reference number of the outline drawing, or drawing of non-standard package including terminal numbering;
c) principal package material, for example, metal, ceramic, plastic.

4.2 Application description

4.2.1 Conformance to system and/or interface information

It should be stated whether the integrated circuit conforms to an application system and/or an interface standard or a recommendation.

Detailed information concerning application systems, equipment and circuits such as very small aperture terminal (VSAT) systems, broadcasting satellite (BS) receivers, microwave landing systems should also be given.

4.2.2 Overall block diagram

A block diagram of the applied systems should be given if necessary.

4.2.3 Reference data

The most important properties that permit comparison between derivative types should be given.

4.2.4 Electrical compatibility

It should be stated whether the integrated circuit is electrically compatible with other particular integrated circuits, or families of integrated circuits, or whether special interfaces are required.

Details should be given concerning the type of input and output circuits, for example input/output impedances, DC block, open-drain. Interchangeability with other devices, if any, should also be given.

4.2.5 Associated devices

If applicable, the following should be stated:

– devices necessary for correct operation (list with type number, name and function);
– peripheral devices with direct interfacing (list with type number, name and function).

4.3 Specification of the function

4.3.1 Detailed block diagram – Functional blocks

A detail block diagram or equivalent circuit information of the integrated circuit microwave frequency multipliers shall be given. The block diagram shall be composed of the following:

a) functional blocks;
b) mutual interconnections among the functional blocks;
c) individual functional units within the functional blocks;
d) mutual interconnections among the individual functional blocks;
e) function of each external connection;
f) inter-dependence between the separate functional blocks.

The block diagram shall identify the function of each external connection and, where no ambiguity can arise, also show the terminal symbols and/or numbers. If the encapsulation has metallic parts, any connection to them from external terminals shall be indicated. The connections with any associated external electrical elements shall be stated, where necessary.

As additional information, the complete electrical circuit diagram can be reproduced, but not necessarily with indications of the values of the circuit components. The graphical symbol for the function shall be given. With respect to the rules governing such diagrams, IEC 60617 applies.

4.3.2 Identification and function of terminals

All terminals shall be identified on the block diagram (supply terminals, input or output terminals, input/output terminals).

The terminal functions 1) to 4) shall be indicated in a table as follows:

Terminal number	Terminal symbol	1) Terminal designation	2) Function	Function of terminal	
				3) Input/output identification	4) Type of input/output circuits

1) Terminal designation

A terminal designation to indicate the function of the terminal shall be given. Supply terminals, ground terminals, blank terminals (with abbreviation NC), non-usable terminals (with abbreviation NU) shall be distinguished.

2) Function

A brief indication of the terminal function shall be given:

– each function of multi-role terminals, i.e. terminals having multiple functions;

– each function of integrated circuit selected by mutual pin connections, programming and/or application of function selection data to the function selection pin, such as mode selection pin.

3) Input/output identification

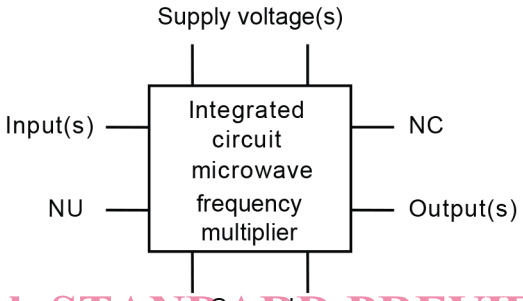
Input, output, input/output and multiplex output terminals shall be distinguished.

4) Type of input/output circuits

The type of input and output circuit, for example input/output impedances, with or without DC block, shall be distinguished.

If the baseplate of the package is used as a ground terminal, the type of ground, for example analog ground, digital ground, shall be stated in the column of 2) Function.

EXAMPLE



4.3.3 Function description

The function performed by the circuit shall be specified, including the following information:

– basic function;
– relation to external terminals;
– operation mode (e.g. set-up method, preference).

4.4 Limiting values (absolute maximum rating system)

4.4.1 Requirements

The table for these values shall contain the following:

– Any interdependence of limiting conditions shall be specified.
– If externally connected and/or attached elements, for example heatsinks, have an influence on the values of the ratings, the ratings shall be specified for the integrated circuit with the elements connected and/or attached.
– If limiting values are exceeded for transient overload, the permissible excess and their durations shall be specified.
– Where minimum and maximum values differ during programming of the device, this shall be stated.
– All voltages are referenced to a specified reference terminal (Vss, ground, etc.).
– If maximum and/or minimum values are quoted, the manufacturer shall indicate whether he refers to the absolute magnitude or to the algebraic value of the quantity.
– The ratings given shall cover the operation of the multi-function integrated circuit over the specified range of operating temperatures. Where such ratings are temperature-dependent, this dependence shall be indicated.

4.4.2 Electrical limiting values

Limiting values shall be specified as follows:

Parameters	Min.	Max.
Bias voltage(s) (where appropriate)		+
Bias current(s) (where appropriate)		+
Terminal voltage(s) (where appropriate)	+	+
Terminal current(s) (where appropriate)		+
Input power		+
Power dissipation		+
It is necessary to select either bias voltage(s) or bias current(s), either terminal voltage(s) or terminal current(s).		

The detail specification may indicate those values within the table including footnotes a and b.

Parameters [a, b]	Symbols	Min.	Max.	Unit

[a] Where appropriate, in accordance with the type of circuit considered.

[b] For power supply voltage range:

- limiting value(s) of the continuous voltage(s) at the supply terminal(s) with respect to a special electrical reference point;
- where appropriate, limiting value between specified supply terminals;
- when more than one voltage supply is required, a statement shall be made as to whether the sequence in which these supplies are applied is significant: if so, the sequence shall be stated;
- when more than one supply is needed, it may be necessary to state the combinations of ratings for these supply voltages and currents.

4.4.3 Temperatures

The detail specification may indicate the following temperature values within the table including the note:

a) operating temperature (ambient or reference-point temperature);

b) storage temperature;

c) channel temperature;

d) lead temperature (for soldering).

Parameters (Note)	Symbols	Min.	Max.	Unit
NOTE Where appropriate, in accordance with the type of circuit considered.				

4.5 Operating conditions (within the specified operating temperature range)

Operating conditions are not to be inspected, but may be used for quality assessment purposes.

a) power supplies – positive and/or negative values;

b) initialization sequences (where appropriate);

If special initialization sequences are necessary, power supply sequencing and initialization procedure shall be specified.

c) input voltage(s) (where appropriate);

d) output current(s) (where appropriate);

e) voltage and/or current of other terminal(s);

f) external elements (where appropriate);

g) operating temperature range.

4.6 Electrical characteristics

The characteristics shall apply over the full operating temperature range, unless otherwise specified. Each characteristic shall be stated either

a) over the specified range of operating temperatures, or

b) at a temperature of 25 °C, and at maximum and minimum operating temperatures.

Parameters	Min.	Typ.	Max.
Bias operating current		+	+
Conversion gain (G_c)	+	+	+
Output power (P_o)	+	+	+
Input return loss ($L_{ret(in)}$)	+	+	
Output return loss ($L_{ret(out)}$)	+	+	
Fundamental isolation (P_o/P_1)	+	+	
n-th order harmonic isolation (P_o/P_{nth})	+	+	
Phase noise ($\mathscr{L}(f)$)		+	+

4.7 Mechanical and environmental ratings, characteristics and data

Any specific mechanical and environmental ratings applicable shall be stated (see also 5.10 and 5.11 of IEC 60747-1:2006).

4.8 Additional information

Where appropriate, the following information shall be given:

a) Equivalent input and output circuit: Detail information shall be given regarding the type of input and output circuits, for example input/output impedances, DC block, open-drain.

b) Internal protection: A statement shall be given to indicate whether the integrated circuit contains internal protection against high static voltages or electrical fields.

c) Capacitors at terminals: If capacitors for the input/output DC block are needed, these capacitances shall be stated.

d) Thermal resistance.

e) Interconnections to other types of circuit: Where appropriate, details of the interconnections to other circuits shall be given.

f) Effects of externally connected component(s): Curves or data indicating the effect of externally connected component(s) that influence the characteristics may be given.

g) Recommendations for any associated device(s): For example, decoupling of power supply to a high-frequency device shall be stated.

h) Handling precautions: Where appropriate, handling precautions specific to the circuit shall be stated (see also IEC 61340-5-1 and IEC TR 61340-5-2).

i) Application data.

j) Other application information.

k) Date of issue of the data sheet.

5 Measuring methods

5.1 General

5.1.1 General precautions

The general precautions listed in 6.3, 6.4 and 6.6 of IEC 60747-1:2006 shall be applied. In addition, special care shall be taken to use low-ripple DC power supplies and to decouple adequately all supply terminals at the frequency of measurement. Although the level of the signal can be specified in either power or voltage, in this document it is expressed in power unless otherwise specified.

5.1.2 Characteristic impedance

The characteristic impedance of the measurement system, shown in the circuit in this document, is 50 Ω. If it is not 50 Ω, it shall be specified.

5.1.3 Handling precautions

When handling electrostatic-sensitive devices, the handling precautions given in IEC 61340-5-1 and IEC TR 61340-5-2 shall be observed.

5.1.4 Types

The devices in this document are both packaged and chip types, measured using suitable test fixtures.

5.2 Output power (P_o)

5.2.1 Purpose

To measure the output power under specified conditions.

5.2.2 Circuit diagram

The measuring circuit is shown in Figure 1.

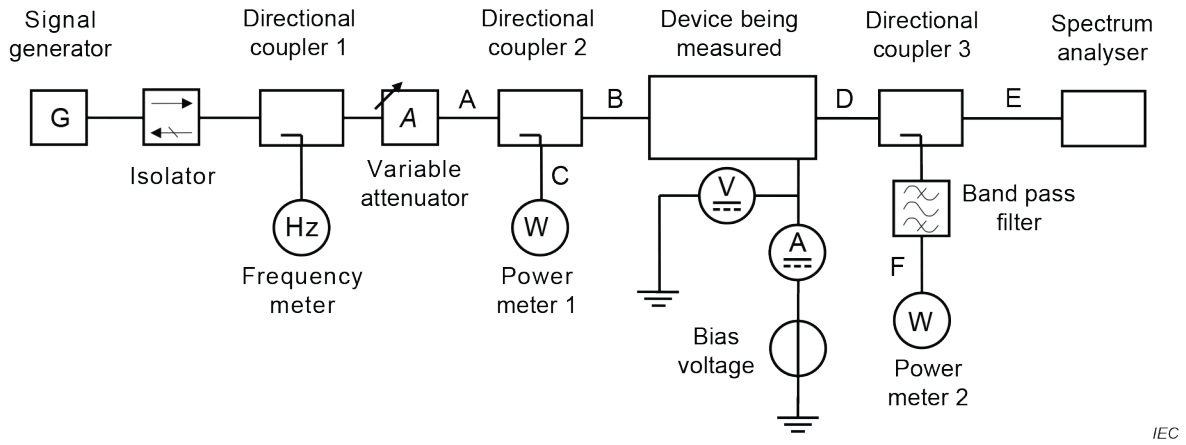


Figure 1 – Circuit diagram for the measurement of the output power

5.2.3 Principle of measurement

In the circuit diagram shown in Figure 1, the input power P_i and output power P_o of the device being measured are derived from the following equations: